

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: Qin-Yi TONG

SERIAL NO: 10/762,318

GAU: 2823

FILED: January 23, 2004

EXAMINER: GARCIA, JOANNE A.

FOR: METHOD FOR LOW TEMPERATURE BONDING AND BONDED STRUCTURE

INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.97

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

SIR:

Applicant(s) wish to disclose the following information.

REFERENCES

- ☒ The applicant(s) wish to make of record the reference(s) listed on the attached Supplementary Partial European Search Report and form PTO-1449. Copies of the listed reference(s) are attached, where required, as are either statements of relevancy or any readily available English translations of pertinent portions of any non-English language reference(s). The two references considered in the parent application are not attached.
- ☐ Online credit card payment is being made in the amount required under 37 CFR §1.17(p).

RELATED CASES

- ☐ Attached is a list of applicant's pending application(s), published application(s) or issued patent(s) which may be related to the present application. In accordance with the waiver of 37 CFR 1.98 dated September 21, 2004, copies of the cited pending applications are not provided. Cited published and/or issued patents, if any, are listed on the attached PTO form 1449.
- ☐ Online credit card payment is being made in the amount required under 37 CFR §1.17(p).

CERTIFICATION

- ☒ Each item of information contained in this information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this statement.
- ☐ No item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned, having made reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this statement.

DEPOSIT ACCOUNT

- ☒ Please charge any additional fees for the papers being filed herewith and for which no check or credit card payment is enclosed herewith, or credit any overpayment to deposit account number 15-0030.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND,
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Form PTO 1449
(Modified)U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICEATTY DOCKET NO.
247830US20CONTSERIAL NO.
10/762,318

LIST OF REFERENCES CITED BY APPLICANT

APPLICANT
Qin-Yi TONGFILING DATE
Janaury 23, 2004GROUP
2823

U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						
	AL						
	AM						
	AN						

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION	
					YES	NO
	AO					
	AP					
	AQ					
	AR					
	AS					
	AT					

OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)

	AU	Andreas Plossl et al., "THE INTERFACE OF SILICON SAMPLES JOINED AT ROOM TEMPERATURE BY WAFER DIRECT BONDING IN ULTRAHIGH VACUUM", Preceedings of the Eighth International Symposium on Silicon Materials Science and Technology, Vol. 2, pp. 1361-1372, 1998.
	AV	C. Gui et al., "PRESENT AND FUTURE ROLE OF CHEMICAL MECHANICAL POLSHING IN WAFER BONDING", Journal of the Electrochemical Society, Vol. 145, No. 6, pp. 2198-2204, June 1998.
	AW	Hideki Takagi et al., "LOW-TEMPERATURE DIRECT BONDING OF SILICON AND SILICON DIOXIDE BY THE SURFACE ACTIVATION METHOD", Sensors and Actuators A, Vol. 70, No. 1-2, pp. 164-170, October 1, 1998.
	AX	
	AY	

☐ Additional References sheet(s) attached

Examiner

Date Considered

*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.